



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



- ▶ Ceramic High Power
- ▶ 6868 3.7t Series
- ▶ UVA 4-in-1 (365/385/405/425nm)

NOM52S80 (UVA 4-in-1)



Release Date: 11 September 2020 Version: A1.0



6868 3.7t Series

RoHS Compliant



FEATURES:

- **Package:** Ceramic SMT Package with Quartz Glass Lens
- **Forward Current:** 4*500mA
- **Forward Voltage (typ.):** 3.5V
- **Radiant Power (typ.):** 550~800mW@500mA
- **Colour:** Ultraviolet (UV)
- **Wavelength:** 365/385/405/425nm
- **Viewing angle:** 60°
- **Materials:**
 - Die: InGaN
 - Resin: Quartz Glass (Water Clear)
 - L/F: AlN
- **Operating Temperature:** -40~+80°C
- **Storage Temperature:** -40~+100°C
- **ESD:** 1KV (HBM: MIL-STD-883 Class 3B)
- **Grouping parameters:**
 - Forward voltage
 - Radiant power
 - Peak Wavelength
- **Soldering methods:** Reflow soldering
- **MSL:** Level 4 according to J-STD020
- **Packing:** 16mm tape with min.100pcs/reel, ø180mm (7")

APPLICATIONS:

- Industrial Curing
- Counterfeit Detection
- Medical Device
- Fluorochemistry
- Bacterial Identification
- Cosmetology
- Magnetic Particle Inspection
- Clean Room Inspection
- Mineralogy

**CHARACTERISTICS:**

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Maximum Forward Current	I _{MAX}	500	mA
Pulse Forward Current (D=0.01s; Duty 1/10)	I _{PF}	700	mA
Reverse Voltage	V _R	-20	V
Reverse Current @5V	I _R	10	μA
Electrostatic Discharge (HBM)	ESD	1000	V
Junction Temperature	T _j	125	°C
Thermal Resistance Junction to Solder Point	R _{THIS}	15	°C/W
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T _{STG}	-40~+100	°C
Solder Temperature	T _{SOL}	260	°C

Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V _F	3.0	---	4.0	V	I _F =500mA
Peak Wavelength	W _P	365	---	370	nm	I _F =500mA
Radiant Power	P _O	550	---	650	mW	I _F =500mA
Peak Wavelength	W _P	380	---	390	nm	I _F =500mA
Radiant Power	P _O	700	---	800	mW	I _F =500mA
Peak Wavelength	W _P	400	---	410	nm	I _F =500mA
Radiant Power	P _O	700	---	800	mW	I _F =500mA
Peak Wavelength	W _P	420	---	430	nm	I _F =500mA
Radiant Power	P _O	700	---	800	mW	I _F =500mA
Viewing Angle	2θ _{1/2}	---	60	---	deg	I _F =500mA

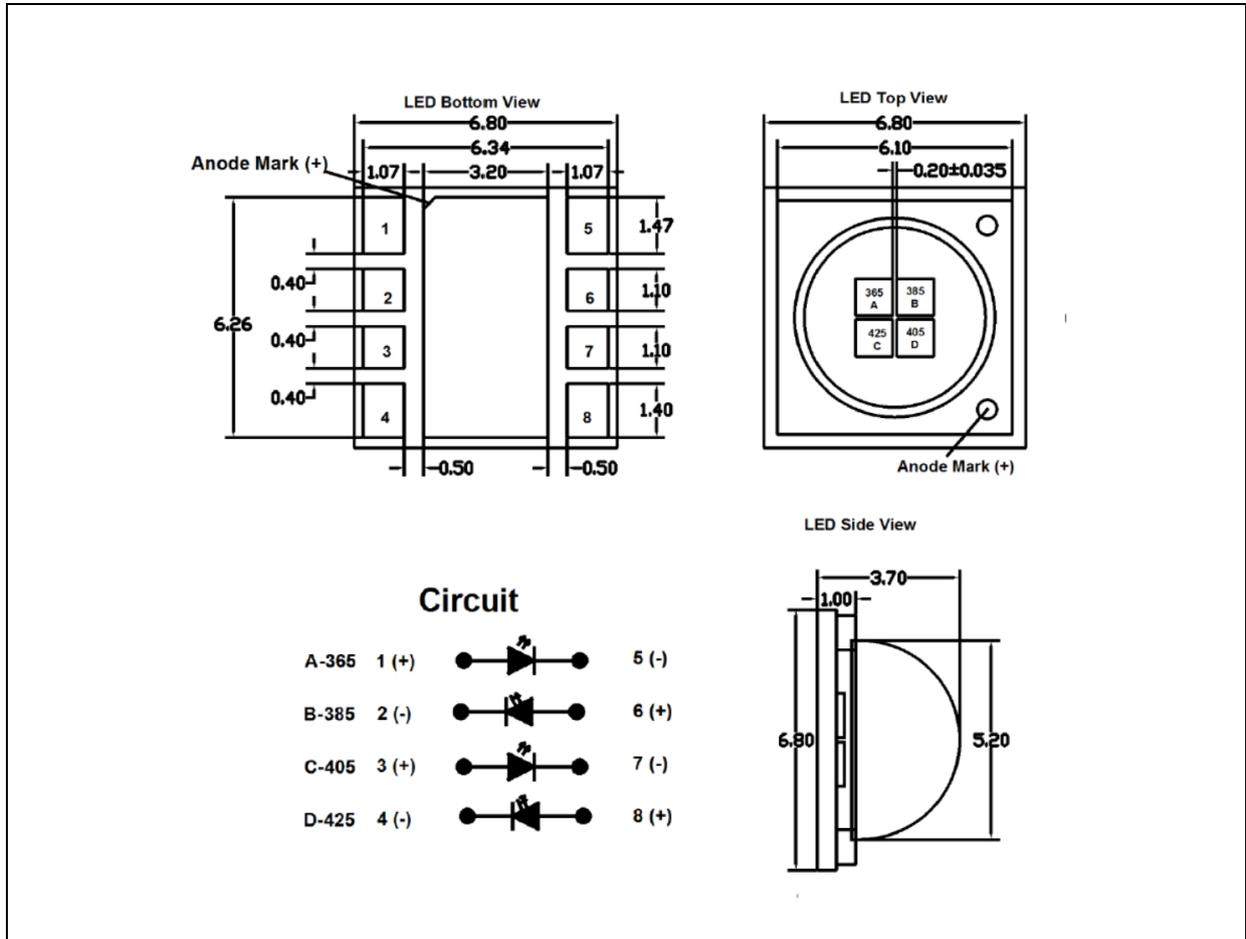
1. Radiant Power (P_O) ±10%, Forward Voltage (V_F) ±0.2V, Viewing angle(2θ_{1/2}) ±10°, Wavelength (nm) ±2nm



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

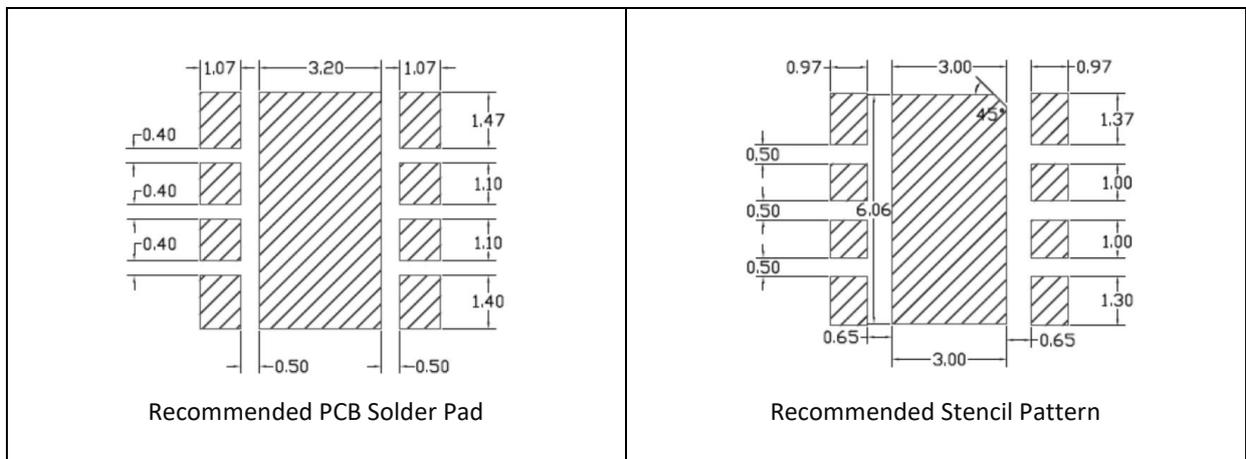
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.13\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.12\text{mm}$ with angle tolerance $\pm 0.5^\circ$.



BINNING GROUPS:

Forward Voltage Classifications ($I_F = 500\text{mA}$):

	Code	Min.	Max.	Unit
V	V365	3.6	4.0	V
	V385	3.2	3.6	
	V405	3.2	3.6	
	V425	3.0	3.4	

Radiant Power Classifications ($I_F = 500\text{mA}$):

	Code	Min.	Max.	Unit
P	PA (365nm)	550	650	mW
	PB (385nm/405nm/425nm)	700	800	

Wavelength Classifications ($I_F = 500\text{mA}$):

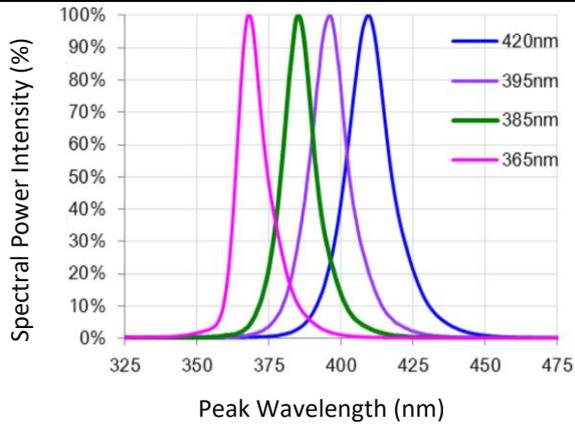
	Code	Min.	Max.	Unit
WL	WL365	365	370	nm
	WL385	380	390	
	WL405	400	410	
	WL425	420	430	



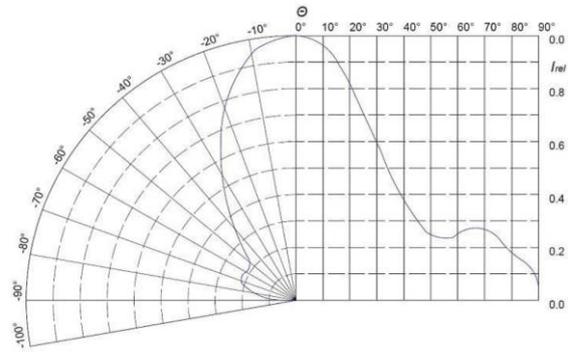
BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

ELECTRO-OPTICAL CHARACTERISTICS:

Relative Spectral Power Distribution



Directive Radiation

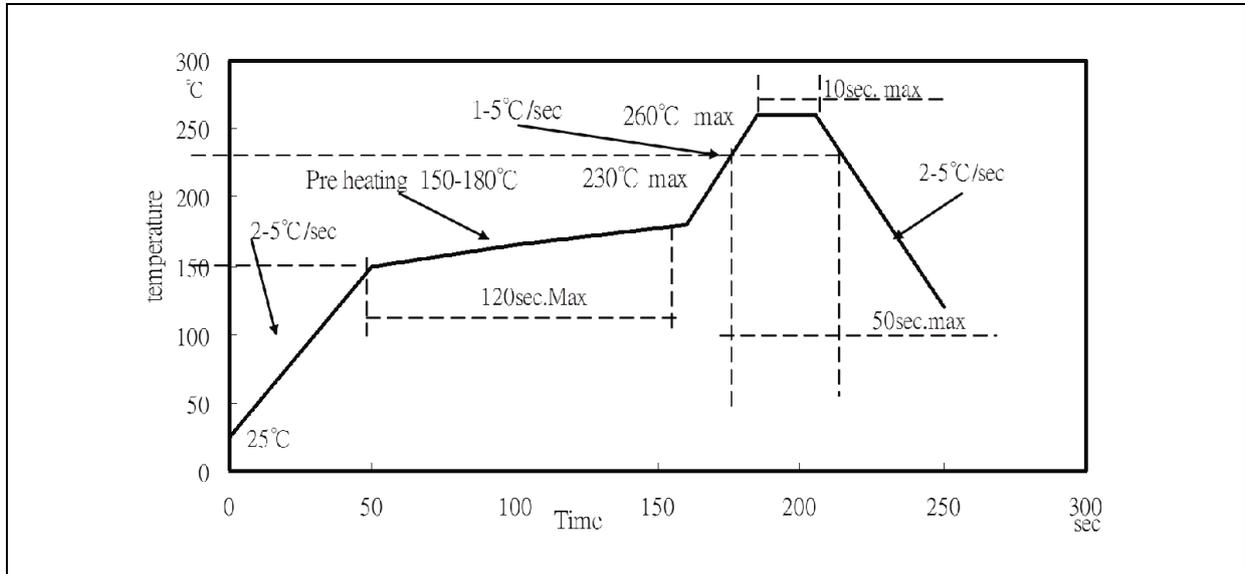




BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



Note:

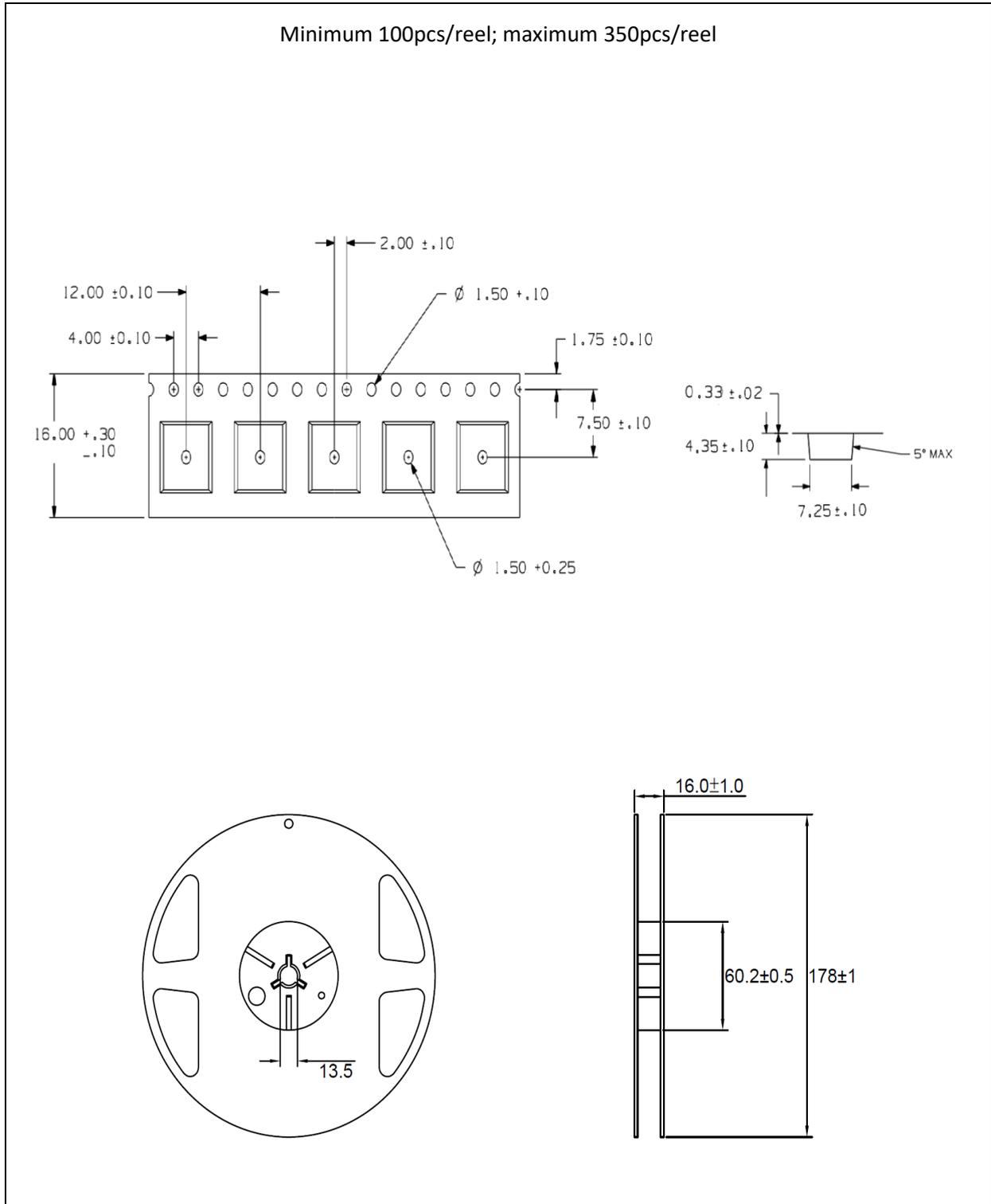
1. Maximum reflow soldering: 2 times.
2. Recommended reflow temperature 240°C. Maximum soldering temperature should be limited to 260°C.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 72 hours. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



BRIGHTEK
BRIGHTEK (EUROPE) LIMITED

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	11/09/2020	Datasheet set-up.